

#### **Features**

- Fast Switching
- Low Gate Charge and R<sub>DS(on)</sub>
- Low Reverse transfer capacitances

## **Product Summary**



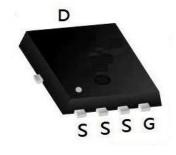
BVDSS	RDSON	ID
120V	10.5mΩ	60A

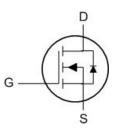
#### **Applications**

- DC-DC converter
- Portable Equipment
- Power management

100% DVDS Tested 100% Avalanche Tested

#### PDFN5060-8L Pin Configuration





#### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	120	V
V <sub>G</sub> S	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	60	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	35	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	220	Α
EAS	Single Pulse Avalanche Energy <sup>3</sup>	210	mJ
las	Avalanche Current		Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	85	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>			°C/W
Rejc	Thermal Resistance Junction-Case <sup>1</sup>		1.47	°C/W



#### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	120			V	
⊿BV <sub>DSS</sub> /⊿T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C,I <sub>D</sub> =1mA				V/°C	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10 V, I <sub>D</sub> =84A		10.5	14	mΩ	
1 103(014)	State Brain Source On Resistance	V <sub>GS</sub> =4.5V , I <sub>D</sub> =84A		12	16		
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> . I <sub>D</sub> =250uA	1.4	1.8	2.2	V	
$\Delta V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	133,15 233				mV/°C	
	Drain Source Leakage Current	V <sub>DS</sub> =120V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =120V, V <sub>GS</sub> =0V , T <sub>J</sub> =125°C			100	- uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA	
gfs	Forward Transconductance	ard Transconductance V <sub>DS</sub> =5V , I <sub>D</sub> =84A				S	
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz				Ω	
Qg	Total Gate Charge			31			
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =60V , V <sub>GS</sub> =10V , I <sub>D</sub> =20A		9.4		nC	
Q <sub>gd</sub>	Gate-Drain Charge			7.5			
T <sub>d(on)</sub>	Turn-On Delay Time			15			
Tr	Rise Time	$V_{DD}$ =60V, $R_{G_{ext}}$ = 5 $\Omega$ ,		10			
T <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> =10V, ID =20A		32		ns	
T <sub>f</sub>	Fall Time			9			
C <sub>iss</sub>	Input Capacitance			1807			
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =60V , V <sub>GS</sub> =0V , f=1MHz		212		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			6			

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			60	А
VsD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =84A , T <sub>J</sub> =250			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	IF=40A ,di/dt=100A / μs ,		60		nS
Qrr	Reverse Recovery Charge	T <sub>J</sub> = 2 5 C		100		nC

<sup>1.</sup> The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

<sup>2.</sup>The data tested by pulsed , pulse width  $\leq 300 us$  , duty cycle  $\leq 2\%$ 

<sup>3.</sup>The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}$ =25V, $V_{\text{GS}}$ =10V,L=0.5mH,

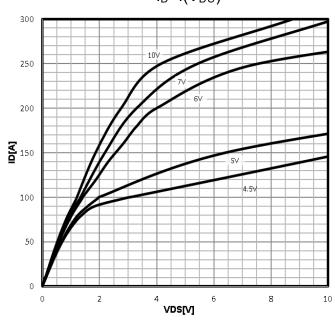
<sup>4.</sup>The power dissipation is limited by 150°C junction temperature

<sup>5.</sup> The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications , should be limited by total power dissipation.

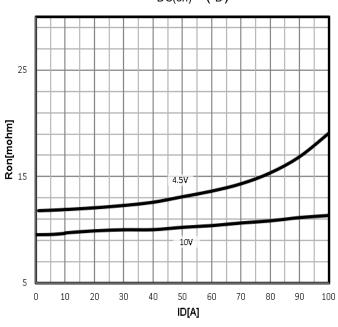


## **Characteristics Curve:**

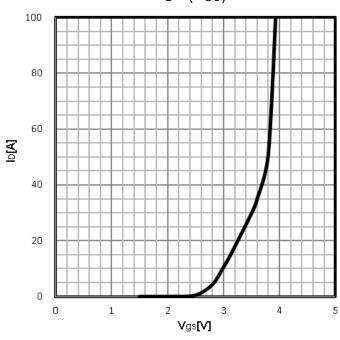
Typ. output characteristics  $I_D = f(V_{DS})$ 



Typ. drain-source on resistance  $R_{DS(on)}=f(I_D)$ 

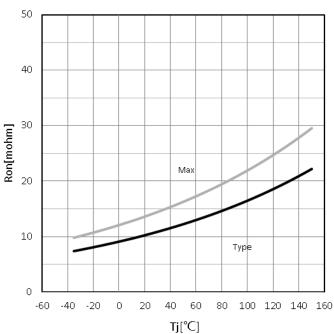


Typ. transfer characteristics  $I_D=f(V_{GS})$ 



**Drain-source on-state resistance** 

 $R_{DS(on)} \!\!=\!\! f(T_j); \ I_D \!\!=\!\! 20A; \ V_{GS} \!\!=\!\! 10V$ 

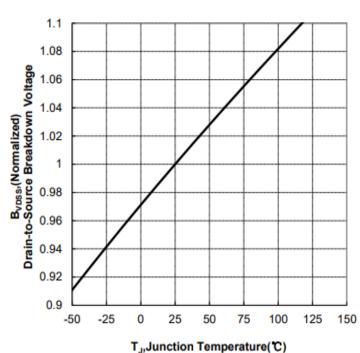


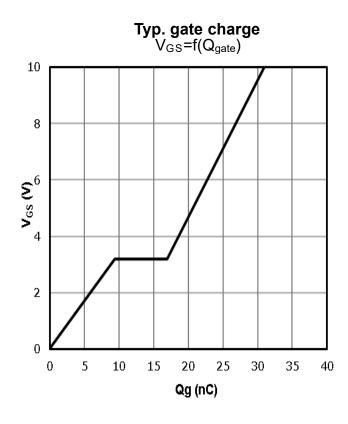


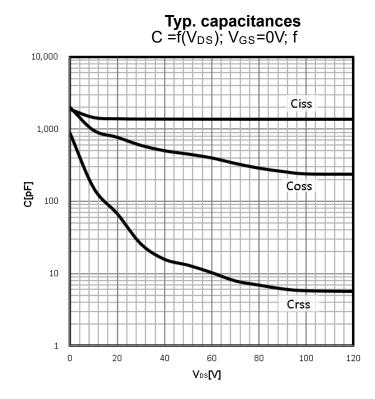
#### **Gate Threshold Voltage** $V_{TH}=f(T_i)$ ; $I_D=250uA$ 1.3 $V_{GS} = V_{DS}$ $I_D = 250\mu A$ 1.2 1.1 V<sub>GS(th)</sub>,(Normalized) Threshold Voltage 1 8.0 0.7 0.6 0.5 -25 25 50 75 100 125 150 -50

T<sub>J</sub>,Junction Temperature(°C)

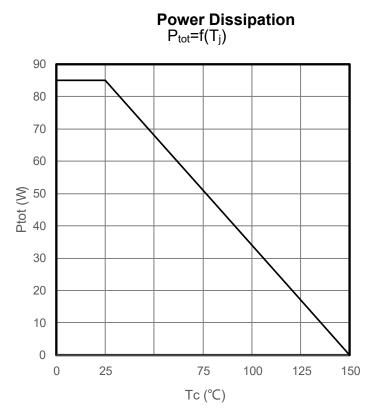
# $\begin{array}{c} \textbf{Drain-source breakdown voltage} \\ V_{BR(DSS)} = f(T_j); \ I_D = 250 uA \end{array}$

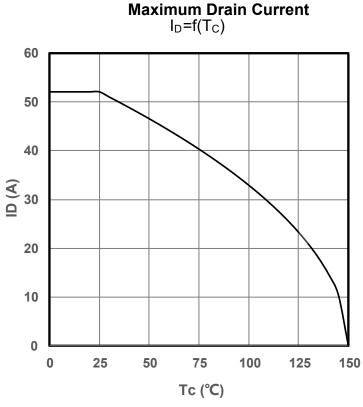


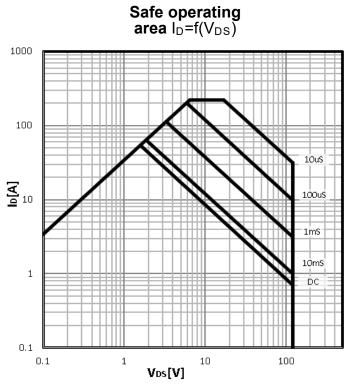


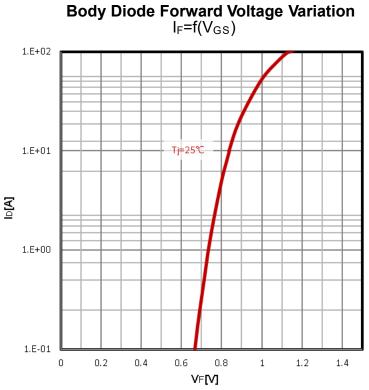








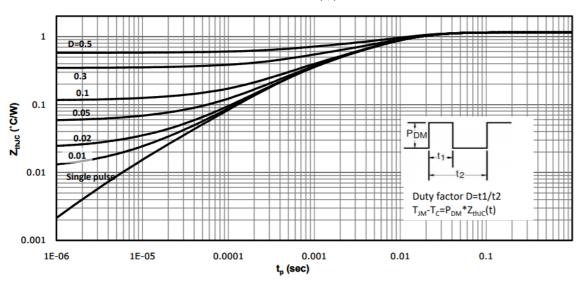






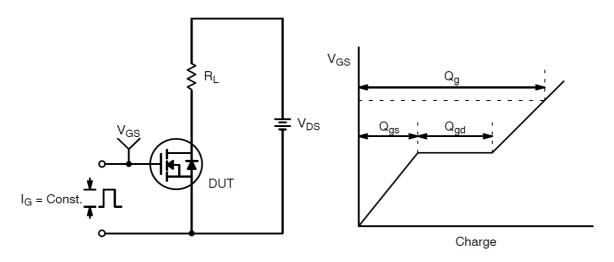
# Max. transient thermal impedance

 $Z_{thJC} = f(t_p)$ 

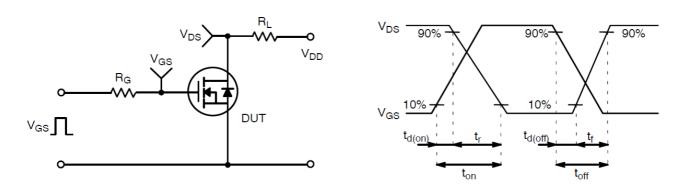




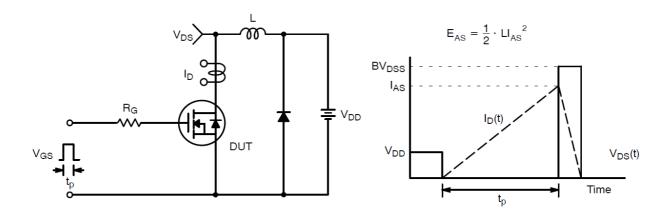
## **Test Circuit and Waveform:**



**Gate Charge Test Circuit & Waveform** 



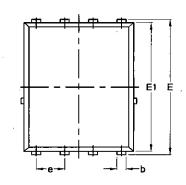
## **Resistive Switching Test Circuit & Waveforms**

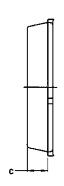


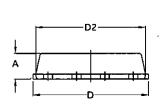
**Unclamped Inductive Switching Test Circuit & Waveforms** 

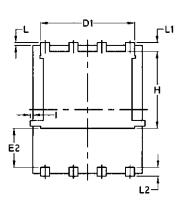


# Package Mechanical Data-PDFN5060-8L-Single









Symbol	Common	Common				
	mm	mm				
	Mim	Max	Min	Max		
Α	1.03	1.17	0.0406	0.0461		
b	0.34	0.48	0.0134	0.0189		
С	0.824	0.0970	0.0324	0.082		
D	4.80	5.40	0.1890	0.2126		
D1	4.11	4.31	0.1618	0.1697		
D2	4.80	5.00	0.1890	0.1969		
E	5.95	6.15	0.2343	0.2421		
E1	5.65	5.85	0.2224	0.2303		
E2	1.60	/	0.0630	/		
е	1.27 BSC	1.27 BSC				
L	0.05	0.25	0.0020	0.0098		
L1	0.38	0.50	0.0150	0.0197		
L2	0.38	0.50	0.0150	0.0197		
Н	3.30	3.50	0.1299	0.1378		
1	/	0.18	/	0.0070		